

# SSL2108X

## Drivers for LED lighting

Rev. 1 — 9 September 2011

Preliminary data sheet

## 1. General description

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The SSL2108X is a range of high-voltage Integrated Circuits (ICs), intended to drive non-dimmable retrofit LED lamps in general lighting applications.

The main benefits of the product family are:

- Small Printed-Circuit Board (PCB) footprint, and compact solution
- High efficiency (up to 95 %)
- Ease of integration
- Low electronic Bill Of Material (BOM)

The product family is made of ICs with a range of internal HV switches for easy power scaling.

The ICs work as boundary conduction mode buck converters. The IC range has been designed to start up directly from the HV supply by an internal high-voltage current source. Followed by the  $dV/dt$  supply using capacitive coupling from the drain, or any other auxiliary supply. This functionality provides full flexibility in the application design. The supply current consumed by the IC is 1 mA, an internal clamp limits the supply voltage.

The ICs provide accurate output current control with greater than 5 % LED current accuracy. The ICs can be operated using Pulse-Width Modulation (PWM) dimming and has many protection features including easy LED temperature feedback.

**Remark:** All voltages unless otherwise specified are in V (AC).

## 2. Features and benefits

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- LED driver IC family driving strings of LEDs from a rectified mains supply
- High-efficiency switch mode buck driver product family:
  - ◆ Drivers with integrated 300 V or 600 V power switches
- Controller with power-efficient boundary conduction mode of operation with:
  - ◆ No reverse recovery losses in freewheel diode
  - ◆ Zero Current Switching (ZCS) for turn-on of switch
  - ◆ Zero voltage or valley switching for turn-on of switch
  - ◆ Minimal required inductance value and size
- Direct PWM dimming possible
- Fast transient response through cycle-by-cycle current control:
  - ◆ Negligible AC mains ripple at LED current and minimal total capacitor value
  - ◆ No over or undershoots in the LED current



- No binning on LED forward voltage required
- Internal Protections:
  - ◆ UnderVoltage LockOut (UVLO)
  - ◆ Leading-Edge Blanking (LEB)
  - ◆ OverCurrent Protection (OCP)
  - ◆ Short-Winding Protection (SWP)
  - ◆ Internal OverTemperature Protection (OTP)
  - ◆ Brownout protection
  - ◆ Output Short Protection (OSP)
- Low component count (see [Figure 4](#)) LED driver solution:
  - ◆ No Schottky diode required due to ZCS
  - ◆ No dim switch and high-side driver required for PWM dimming
  - ◆ Easy external temperature protection without additional components
  - ◆ Option for soft-start function
  - ◆ Hotaru switch compatible during standby<sup>1</sup>
- IC lifetime easily matches or surpasses LED lamp lifetime

### 3. Applications

- SSL2108X products are intended for compact LED lamp ballasts with accurate fixed current output for single mains input voltages. Mains input voltages include 100 V, 120 V and 230 V (AC). The output signal can be modulated using a PWM signal.

### 4. Quick reference data

**Table 1. Quick reference data**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		9.5	-	15.5	V
$R_{DSon}$	drain-source on-state resistance	600 V version, $T_J = 25\text{ }^\circ\text{C}$	4.0	5.0	6.0	$\Omega$
		600 V version, $T_J = 125\text{ }^\circ\text{C}$	6.5	7.5	8.5	$\Omega$
		300 V version, $T_J = 25\text{ }^\circ\text{C}$	1.75	2.0	2.25	$\Omega$
		300 V version, $T_J = 125\text{ }^\circ\text{C}$	2.75	3.0	3.25	$\Omega$
$f_{conv}$	conversion frequency		25	-	200	kHz
$I_{DRAIN}$	current on pin DRAIN	600 V version	-1	-	1	A
		300 V version	-2	-	2	A
$V_{DRAIN}$	voltage on pin DRAIN	600 V version	-	-	600	V
		300 V version	-	-	300	V
$t_{on}$	turn-on time		-	-	16	$\mu\text{s}$

1. Hotaru switch is a wall-switch with build-in light that is activated when wall-switch is in off position.

## 5. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
SSL21081 SSL21083	SO8	plastic small package outline body; 8 leads; body width 3.9 mm	SOT96-1
SSL21082 SSL21084	SO12	plastic small package outline body; 12 leads; body width 3.9 mm	SOT119 6-1

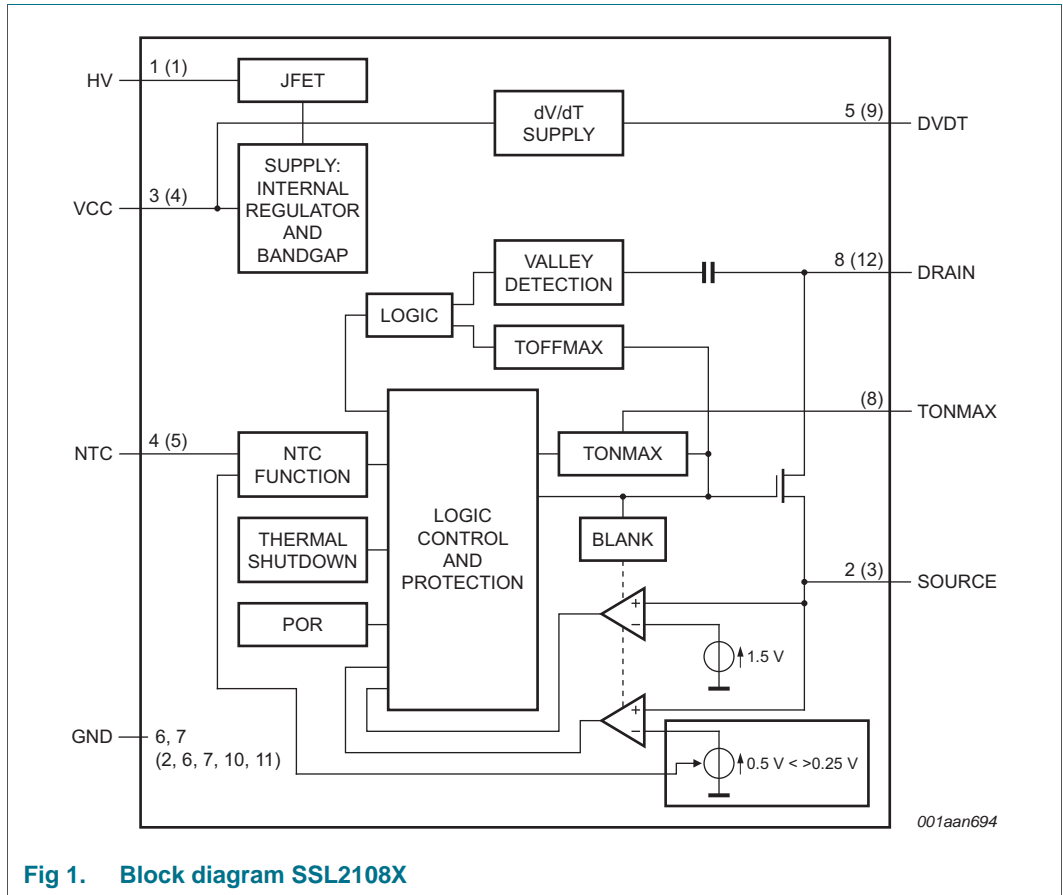
### 5.1 Ordering options

Table 3. Ordering options

SSL2108 platform variants	Input voltage range	Internal MOSFET characteristics	Package	Brownout protection selectable
SSL21081	100 V; 120 V	300 V; 2 $\Omega$	SO8	no
SSL21082	100 V; 120 V	300 V; 2 $\Omega$	SO12	yes
SSL21083	100 V; 120 V; 230 V	600 V; 5 $\Omega$	SO8	no
SSL21084	100 V; 120 V; 230 V	600 V; 5 $\Omega$	SO12	yes

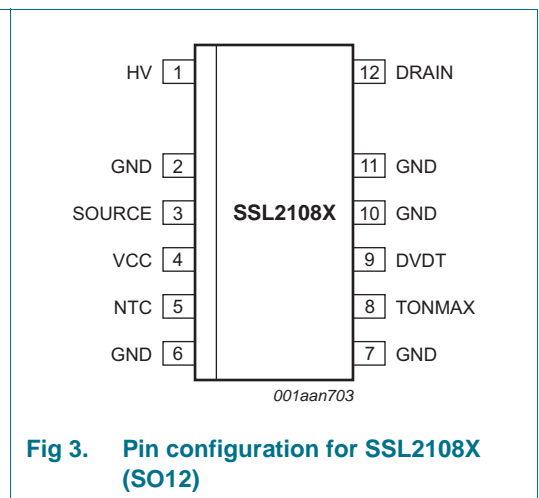
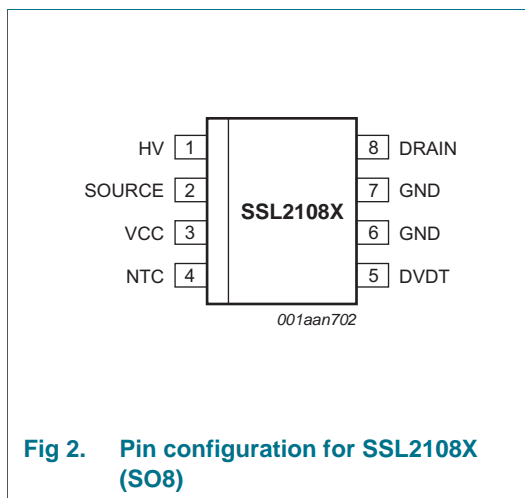
[1] The SO12 package variants have more so called fused leads and can be used when higher output power is required.

## 6. Block diagram



## 7. Pinning information

### 7.1 Pinning



## 7.2 Pin description

Table 4. Pin description

Symbol	Pin (SO8) SSL2108X	Pin (SO12) SSL2108X	Description
HV	1	1	high-voltage supply pin
SOURCE	2	3	low-side internal switch
VCC	3	4	supply voltage
NTC	4	5	LED temperature protection input
GND	6, 7	2,6,7,10,11	ground
DVDT	5	9	AC supply pin
TONMAX	-	8	brownout protection timer input
DRIVER	-	-	driver output
DRAIN	8	12	high-side internal switch

## 8. Functional description

### 8.1 Introduction

The SSL2108X is a product range of ICs intended for retrofit small form factor SSL lamps. They provide a controller/driver with internal high-voltage switch.

### 8.2 Converter operation

The converter in the SSL2108X is a Boundary Conduction Mode (BCM), peak current controlled system. For the basic application diagram see [Figure 4](#), for the waveforms see [Figure 5](#). This converter type operates at the boundary between continuous and discontinuous mode. Energy is stored in inductor L each period that the switch is on. The inductor current  $I_L$  is zero when the internal MOSFET switch is switched on. Thereafter, the amplitude of the current build-up in L is proportional to  $V_{IN} - V_{OUT}$  and the time that the internal MOSFET switch is on. When the internal MOSFET switch is switched off, the current continues to flow through the freewheel diode and the output capacitor. The current then falls at a rate proportional to the value of  $V_{OUT}$ . The LED current  $I_{LED}$  is almost equal to half the peak switch current. A new cycle is started, as soon as the inductor current  $I_L$  is zero.

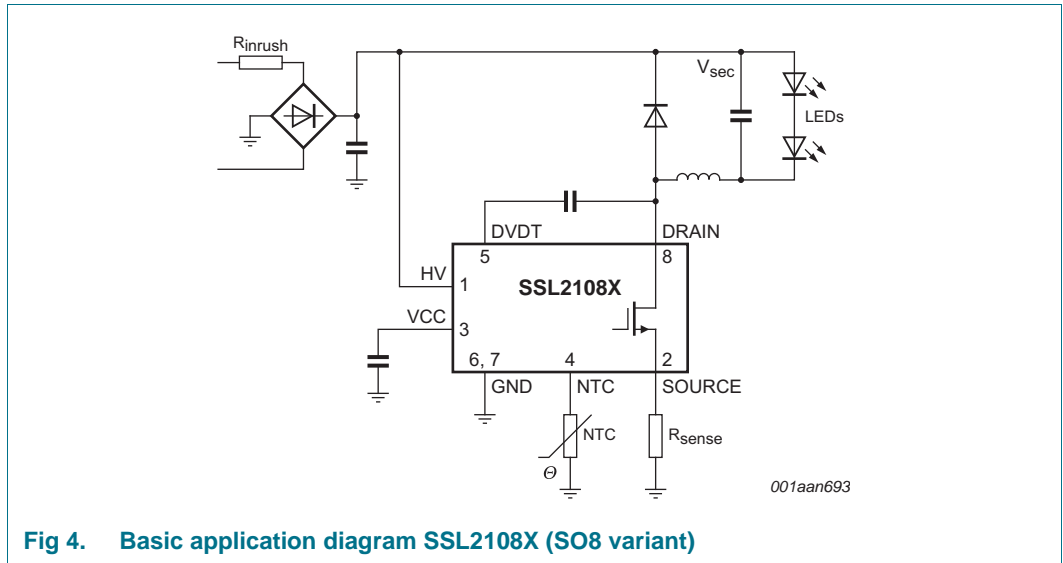


Fig 4. Basic application diagram SSL2108X (SO8 variant)

### 8.3 Conversion frequency

The maximum conversion frequency is 200 kHz. Therefore, select an inductance value that with the given supply voltage, LED voltage and component spread the conversion frequency is always within limits.

### 8.4 Valley detection

A new cycle is started when the primary switch is switched on see [Figure 5](#). Following time  $t_1$ , when the peak current is detected on the SOURCE pin, the switch is turned off and the secondary stroke starts  $t_3$ . When the secondary stroke is completed with the coil current at  $t_3$  equaling zero, the drain voltage starts to oscillate at approximately  $V_{IN} - V_{OUT}$  level. The amplitude equals  $V_{OUT}$ . A special feature, called valley detection is an integrated part of the SSL2108X circuitry. Dedicated built-in circuitry connected to the DRAIN pin, senses when the voltage on the drain of the switch has reached its lowest value. The next cycle is then started and as a result the capacitive switching losses are reduced. A valley is detected and accepted if both the frequency of the oscillations and the voltage swing are within the range specified ( $f_{ring}$  and  $\Delta V_{vrec(min)}$ ) for detection. If a valid valley is not detected, the secondary stroke is continued until the maximum off-time ( $t_{off(high)}$ ) is reached, then the next cycle is started.

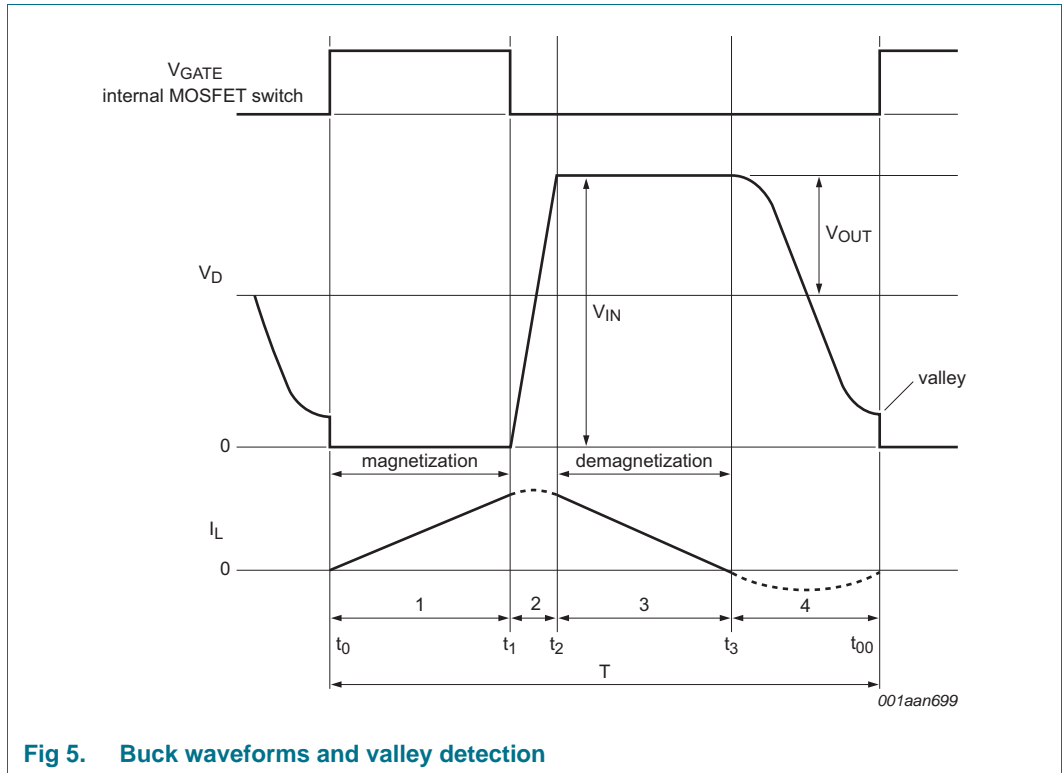


Fig 5. Buck waveforms and valley detection

## 8.5 Protections

The IC has the following protections:

- UnderVoltage LockOut (UVLO)
- Leading-Edge Blanking (LEB)
- OverCurrent Protection (OCP)
- Internal OverTemperature Protection (OTP)
- Brownout protection
- Short-Winding Protection (SWP)
- Output Short Protection (OSP)
- LED overtemperature control and protection

The SWP and the OSP are latched protections. These protections cause the IC to halt until a reset (caused by power cycling) is executed. When  $V_{CC}$  drops lower than  $V_{CC(rst)}$ , the IC resets the latch protection mode. The internal OTP and LED over temperature protections are safe-restart protections. The IC halts, causing  $V_{CC}$  to fall lower than  $V_{CC(stop)}$ , and instigates start-up. Switching starts only when no fault condition exists.

### 8.5.1 UnderVoltage LockOut (UVLO)

When the voltage on the VCC pin drops lower than  $V_{CC(stop)}$ , the IC stops switching. An attempt is then made to restart by supplying  $V_{CC}$  from the HV pin voltage.

### 8.5.2 Leading-Edge Blanking (LEB)

To prevent false detection of the short-winding or overcurrent, a blanking time following switch-on is implemented. When the internal MOSFET switch opens there can be a short current spike due to capacitive discharge of voltage over the drain and source. During the LEB time  $t_{leb}$  is disregarded.

### 8.5.3 OverCurrent Protection (OCP)

The SSL2108X contains a highly accurate peak current detector. It triggers when the voltage at the SOURCE pin reaches the peak-level  $V_{th(ocp)SOURCE}$ . The current through the switch is sensed using a resistor connected to the SOURCE pin. The sense circuit is activated following LEB time  $t_{leb}$ . As the LED current is half the peak current (by design), this state automatically provides protection for maximum LED current during operation. There is a propagation delay between overcurrent detection and the actual closure of the switch  $t_{d(ocp-swoff)}$ . Due to the delay, the actual peak current is slightly higher than the OCP level set by the resistor in series to the SOURCE pin.

### 8.5.4 OverTemperature Protection (OTP)

When the internal OTP function is triggered at a certain IC temperature ( $T_{th(act)otp}$ ), the converter stops operating. The OTP safe-restart protection and the IC restarts again with switching resuming when the IC temperature drops lower than  $T_{th(rel)otp}$ .

### 8.5.5 Brownout protection

Brownout protection is designed to limit the lamp power when the input voltage drops close to the output voltage level. In constant power mode, the input current would otherwise increase to a level that is too large for the input circuitry. In the SSL2108X, there is a maximum limit on the on-time of switch  $t_{on(high)}$ . Since the rate of current rise in the coil during the on-phase is proportional to the difference between input voltage and output voltage, the peak current cannot be reached before  $t_{on(high)}$ . Therefore, the average output current to the LEDs is reduced.

Using the SO12 package, the  $t_{on(high)}$  can be lowered by connecting a capacitor to the TONMAX pin. The external capacitor is charged during the primary stroke with  $I_{TONMAX}$ . If  $V_{TONMAX}$  level is reached before the  $t_{on(high)}$  time, the switch is turned off and the secondary stroke starts. When no capacitor is connected to the pin,  $V_{TONMAX}$  is reached quickly, shorter than the minimum limit of microsecond. In this case, or in case the TONMAX pin is grounded, the internal time constant,  $t_{on(high)}$  determines the maximum on-time.

### 8.5.6 Short-Winding Protection (SWP)

SWP activates if there is a steep rising MOSFET current through the external resistor connected to the SOURCE pin. This current can occur when there is a short from the freewheel diode. Additionally, it occurs due to a small/shorted inductor between the input voltage and the DRAIN pin. If the voltage on the SOURCE pin is greater than 1.5 V, latched protection is triggered following LEB time  $t_{leb}$ . In addition, if  $V_{CC}$  drops lower than  $V_{CC(rst)}$  the IC resets the latched protection mode.

### 8.5.7 Output Short Protection (OSP)

During the second stroke (switch-off time), if a valley is not detected within the off-time limit ( $t_{off(high)}$ ), it is likely that the output voltage is less than the minimum limit allowed in the application. This condition can occur either during starting up or due to a short. A timer is



started when  $t_{\text{off}(\text{high})}$  is detected, and is stopped only if a valid valley-detection occurs in one of the subsequent cycles. If no valley is detected for  $t_{\text{det}(\text{sc})}$ , it is concluded that a real short-circuit exists and not start-up. The IC enters latched protection. If  $V_{\text{CC}}$  drops lower than  $V_{\text{CC}(\text{rst})}$ , the IC resets the latched protection mode. During PWM dimming, the OSP timer is paused during the off-cycle.

## 8.6 VCC supply

The SSL2108X can be supplied using three methods:

- Under normal operation, the voltage swing on the DVDT pin is rectified within the IC providing current towards the VCC pin
- At start-up, there is an internal current source connected to the HV pin. The current source provides internal power until either the dV/dt supply or an external current on the VCC pin provides the supply
- An external voltage source can be connected to the VCC pin

The IC starts up when the voltage at the VCC pin is higher than  $V_{\text{CC}(\text{startup})}$ . The IC locks out (stops oscillating) when the voltage at the VCC pin is lower than  $V_{\text{CC}(\text{stop})}$ . The hysteresis between the start and stop levels allows the IC to be supplied by a buffer capacitor until the dV/dt supply is settled. The SSL2108X has an internal  $V_{\text{CC}}$  clamp, which is an internal active Zener (or shunt regulator). This internal active Zener limits the voltage on the supply VCC pin to the maximum value of  $V_{\text{CC}}$ . If the maximum current of the dV/dt supply minus the current consumption of the IC (determined by the load on the gate drivers), is lower than the maximum value of  $I_{\text{DD}}$  no external Zener diode is needed in the dV/dt supply circuit.

## 8.7 DVDT supply

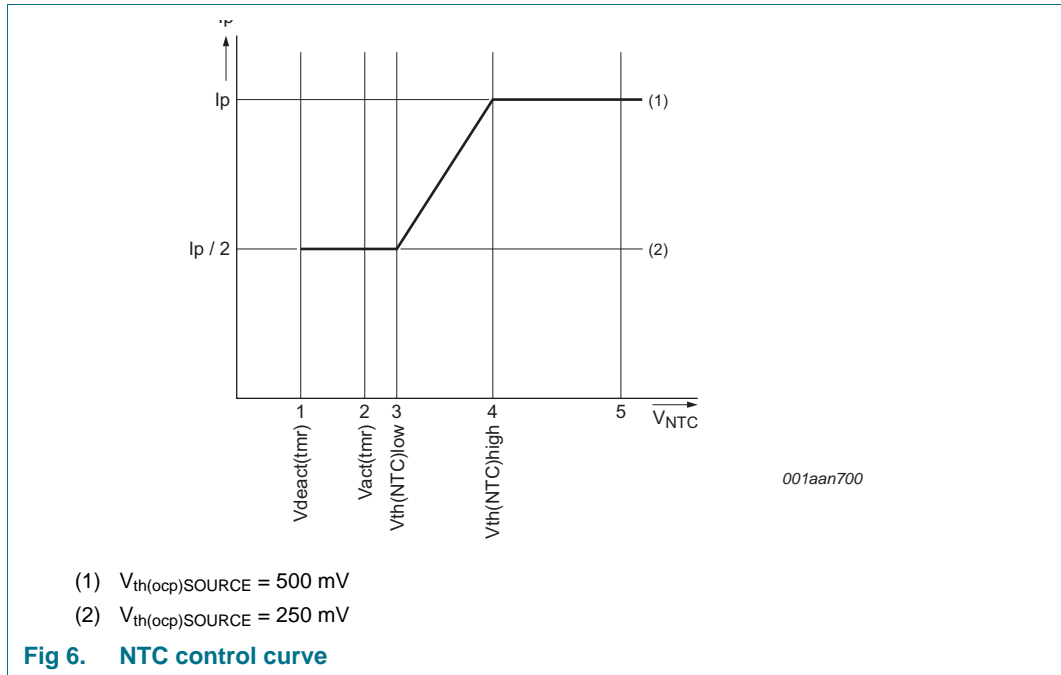
The DVDT pin is connected to an internal single-sided rectification stage. When an alternating voltage with sufficient amplitude is supplied to the pin, the IC can be powered without any other external power connection. This solution provides an effective method to stop the introduction of high-power losses, without the need for additional inductor windings.

## 8.8 VCC regulator

During supply dips, the input voltage can drop too low to supply the required IC current through the DVDT pin. Under these conditions, if the VCC voltage drops lower than  $V_{\text{CC}(\text{swon})\text{reg}}$  level, another regulator with a current capability of up to  $I_{\text{HV}(\text{high}(\text{oper}))}$  is started. The job of the regulator is to fill in the required supply current, which the DVDT supply does not deliver preventing the IC going into UVLO. When the VCC voltage is higher than  $V_{\text{CC}(\text{swon})\text{reg}}$  level, the regulator is turned off.

## 8.9 NTC functionality and PWM dimming

The NTC pin can be used as a control method for LED thermal protection. Alternatively, the pin can be used as an input to disable/enable light output using a digital signal (PWM dimming). The pin has an internal current source that generates the current of  $I_{\text{offset}(\text{NTC})}$ . An NTC resistor to monitor the LED temperature can be directly connected to the NTC pin. However, depending on the resistance value and the corresponding voltage on the NTC pin, the converter reacts as shown in [Figure 6](#).



When the voltage on the NTC pin is higher than  $V_{th(high)NTC}$  see [Figure 6](#) (4), the converter delivers nominal output current. Lower than this voltage level, the peak current is gradually reduced until  $V_{th(low)NTC}$  is reached, see [Figure 6](#) (3). The peak current is now half the peak current of nominal operation. When  $V_{act(tmr)NTC}$  is passed, see [Figure 6](#) (2) a timer starts to run to distinguish between the following:

- If the low-level  $V_{deact(tmr)NTC}$  is not reached within time  $t_{to(deact)NTC}$ , [Figure 6](#) (1) LED overtemperature is detected. The IC stops switching and attempts to restart from the HV pin voltage. Restart only takes place after the voltage on NTC pin is higher than  $V_{th(high)NTC}$ , see [Figure 6](#) (4). It is assumed that the reduction in peak current did not result in a lower NTC temperature and LED OTP is activated.
- If the low-level  $V_{deact(tmr)NTC}$  is reached within the time  $t_{to(deact)NTC}$ , [Figure 6](#) (1) it is assumed that the pin is pulled down externally. The restart function is not triggered. Instead, the output current is reduced to zero. PWM dimming can be implemented this way. The output current rises again when the voltage is higher than  $V_{deact(tmr)NTC}$ .

### 8.9.1 Soft-start function

The NTC pin can be used to make a soft start function. During switch-on, the level on the NTC pin is low. By connecting a capacitor (in parallel with the NTC resistor), a time constant can be defined. The time constant causes the level on the NTC pin to increase slowly. When passing level  $V_{th(low)NTC}$  [Figure 6](#) (3), the convertor starts with half of the maximum current. The output current slowly increases to maximum when  $V_{th(high)NTC}$  [Figure 6](#) (4) is reached.

### 8.10 Heat sink

For SSL2108X (SO12) applications a copper heat sink forms part of PCB. The SSL2108X (SO12) uses thermal leads (pins 2, 6, 10 and 11) for heat transfer from die to the PCB copper heat sink. Enhanced thermal lead connection can drastically reduce thermal resistance.

Equation 1 shows the relation between the maximum allowable power dissipation P and the thermal resistance from junction to ambient.

$$R_{th(j-a)} = (T_{j(max)} - T_{amb}) / P \tag{1}$$

Where:

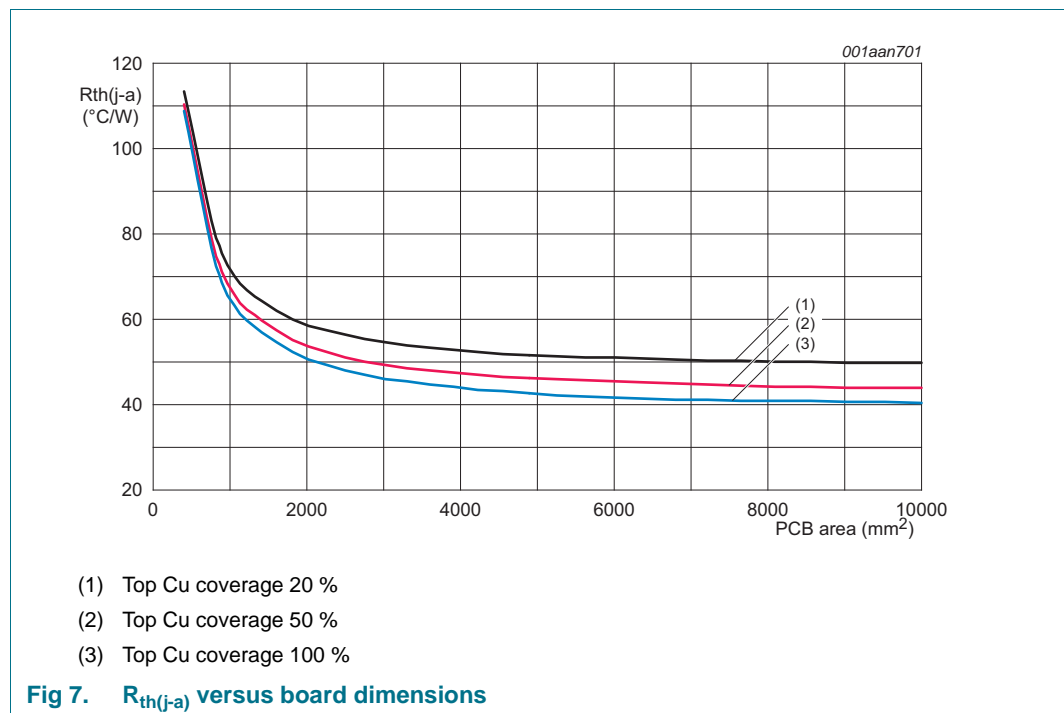
$R_{th(j-a)}$  = thermal resistance from junction to ambient

$T_{j(max)}$  = maximum junction temperature

$T_{amb}$  = ambient temperature

P = power dissipation

The thermal resistance as a function of the PCB area (Board: 0.8 mm thickness, 2 layers, Bottom Cu coverage 90 %, Cu thickness 70 μm (390 W/mK), Core material conductivity: 0.5 W/mK, 10 vias diameter 0.3 mm) is shown in Figure 7.



## 9. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>General</b>					
SR	slew rate	on pin DRAIN	-5	+5	V/ns
f <sub>conv</sub>	conversion frequency		25	200	kHz
P <sub>tot</sub>	total power dissipation	SO8 package	-	0.6	W
		SO12 package	-	1	W
T <sub>amb</sub>	ambient temperature		-40	+125	°C
T <sub>j</sub>	junction temperature		-40	+150	°C
T <sub>stg</sub>	storage temperature		-55	+150	°C
<b>Voltages</b>					
V <sub>CC</sub>	supply voltage	continuous [3]	-0.4	+14	V
V <sub>DRAIN</sub>	voltage on pin DRAIN	600 V version	-0.4	+600	V
		300 V version	-0.4	+300	V
V <sub>HV</sub>	voltage on pin HV	current limited	-0.4	+600	V
V <sub>SENSE</sub>	voltage on pin SENSE	current limited	-0.4	+5.4	V
V <sub>NTC</sub>	voltage on pin NTC	current limited	-0.4	+5.4	V
V <sub>TONMAX</sub>	voltage on pin TONMAX	current limited	-0.4	+5.4	V
<b>Currents</b>					
I <sub>DD</sub>	supply current	at pin VCC [3]	-	20	mA
I <sub>DRAIN</sub>	current on pin DRAIN	600 V version	-1	1	A
		300 V version	-2	2	A
I <sub>SOURCE</sub>	current on pin SOURCE	600 V version	-1	1	A
		300 V version	-2	2	A
I <sub>DVDT</sub>	current on pin DVDT		-	1.3	A
V <sub>ESD</sub>	electrostatic discharge voltage	human body model; (for all pins except DRAIN and HV) [1]	-2.0	+2.0	KV
		human body model for DRAIN and HV	-1.0	+1.0	KV
		charged device [2]	-500	+500	V

[1] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

[2] Charged device model: equivalent to charging the IC up to 1 kV and the subsequent discharging of each pin down to 0 V over a 1 Ω resistor.

[3] An internal clamp sets the supply voltage and current limits.

## 10. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; SO8 package, PCB: 2 cm × 3 cm, 2-layer, 35 μm Cu per layer	152	K/W
		in free air; SO12 package, PCB: 2 cm × 3 cm, 2-layer, 35 μm Cu per layer	121	K/W

## 11. Characteristics

**Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>High-voltage</b>						
$I_{leak(DRAIN)}$	leakage current on pin DRAIN	$V_{DRAIN} = 600\text{ V}$	-	30	60	μA
		$V_{DRAIN} = 300\text{ V}$	-	20	40	μA
$I_{leak(HV)}$	leakage current on pin HV	$V_{HV} = 600\text{ V}$	-	-	10	μA
		$V_{HV} = 300\text{ V}$	-	-	10	μA
<b>Supply</b>						
$V_{CC(startup)}$	start-up supply voltage		11	12	13	V
$V_{CC(stop)}$	stop supply voltage		8	9	10	V
$V_{CC(hys)}$	hysteresis of supply voltage	between $V_{CC(startup)}$ and $V_{CC(stop)}$	2.0	-	-	V
$V_{CC(rst)}$	reset supply voltage		4.5	5	5.5	V
$V_{CC(swon)reg}$	regulator switch-on supply voltage	insufficient dV/dt supply	9	9.5	10	V
$V_{CC(swoff)reg}$	regulator switch-off supply voltage	insufficient dV/dt supply	9.5	10	10.5	V
$V_{CC(reg)hys}$	regulator supply voltage hysteresis	$V_{CC(swoff)reg} - V_{CC(swon)reg}$	0.3	-	-	V
$V_{CC(regswon-stop)}$	supply voltage difference between regulator switch-on and stop	$V_{CC(swon)reg} - V_{CC(stop)}$	0.3	-	-	V
<b>Consumption</b>						
$I_{stb(HV)}$	standby current on pin HV	during start-up or in protection; $V_{HV} = 100\text{ V}$	300	350	400	μA
$I_{CC}$	supply current	normal operation	-	1.3	-	mA

Table 7. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Capability</b>						
$I_{sup(high)HV}$	high supply current on pin HV	Standby: $V_{HV} = 40\text{ V};$ $V_{CC} < V_{CC(stop)}$	1	1.3	1.6	mA
		Regulator On: $V_{HV} = 40\text{ V}; V_{CC} <$ $V_{CC(swon)reg}$ after start-up	2	2.3	2.6	mA
<b>Current and SWP</b>						
$V_{th(ocp)SOURCE}$	overcurrent protection threshold voltage on pin SOURCE	$\Delta V/\Delta t = 0.1\text{ V}/\mu\text{s}$	480	500	520	mV
		$\Delta V/\Delta t = 0.1\text{ V}/\mu\text{s}$ $V_{NTC} = 0.325\text{ V}$	230	250	270	mV
$t_{d(ocp-swoff)}$	delay time from overcurrent protection to switch-off	$\Delta V/\Delta t = 0.1\text{ V}/\mu\text{s}$	-	75	100	ns
$t_{leb}$	leading edge blanking time	overcurrent protection	260	300	340	ns
		short-winding protection	210	250	290	ns
$t_{leb(ocp-swop)}$	leading edge blanking time from overcurrent protection to short-winding protection		30	50	-	ns
$V_{th(swp)SOURCE}$	short-winding protection threshold voltage on pin SOURCE		1.4	1.5	1.6	V
<b>Valley detection</b>						
$(\Delta V/\Delta t)_{vrec}$	valley recognition voltage change with time	on pin DRAIN	-30	-20	-10	V/ $\mu\text{s}$
$f_{ring}$	ringing frequency		200	550	1000	kHz
$\Delta V_{vrec(min)}$	minimum valley recognition voltage difference	voltage drop on pin DRAIN	15	20	25	V
$t_{d(vrec-swon)}$	valley recognition to switch-on delay time		-	100	-	ns
<b>Brownout detection</b>						
$V_{th(TONMAX)}$	threshold voltage on pin TONMAX		3.75	4	4.25	V
$I_{offset(TONMAX)}$	offset current on pin TONMAX		-37	-40	-43	$\mu\text{A}$
$t_{on(high)}$	high on-time		12.5	15	17.5	$\mu\text{s}$
<b>MOSFET output stage</b>						
$V_{BR(DRAIN)}$	breakdown voltage on pin DRAIN	600 V version; $T_j > 0\text{ }^\circ\text{C}$	600	-	-	V
		300 V version; $T_j > 0\text{ }^\circ\text{C}$	300	-	-	V

Table 7. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
R <sub>DSon</sub>	drain-source on-state resistance	600 V version; T <sub>j</sub> = 25 °C	4.0	5.0	6.0	Ω	
		600 V version; T <sub>j</sub> = 125 °C	6.5	7.5	8.5	Ω	
		300 V version; T <sub>j</sub> = 25 °C	1.75	2.0	2.25	Ω	
		300 V version; T <sub>j</sub> = 125 °C	2.75	3.0	3.25	Ω	
t <sub>f(DRAIN)</sub>	fall time on pin DRAIN	300 V version; C <sub>DRAIN</sub> = 150 pF, R <sub>SOURCE</sub> = 2.2 Ω	[1]	-	1.2	-	V/ns
		600 V version; C <sub>DRAIN</sub> = 75 pF, R <sub>SOURCE</sub> = 1.2 Ω	-	-	1.5	-	V/ns
<b>NTC functionality</b>							
V <sub>th(high)NTC</sub>	high threshold voltage on pin NTC		0.47	0.5	0.53	V	
V <sub>th(low)NTC</sub>	low threshold voltage on pin NTC		0.325	0.35	0.375	V	
V <sub>act(tmr)NTC</sub>	timer activation voltage on pin NTC		0.27	0.3	0.325	V	
V <sub>deact(tmr)NTC</sub>	timer deactivation voltage on pin NTC		0.15	0.2	0.25	V	
t <sub>to(deact)NTC</sub>	deactivation time-out time on pin NTC		32	40	48	μs	
I <sub>offset(NTC)</sub>	offset current on pin NTC		-44	-47	-50	μA	
<b>OSP</b>							
t <sub>det(sc)</sub>	short-circuit detection time		16	20	24	ms	
t <sub>off(high)</sub>	high off-time		30	36	42	μs	
<b>Temperature protections</b>							
T <sub>th(act)otp</sub>	overtemperature protection activation threshold temperature		160	170	180	°C	
T <sub>th(rel)otp</sub>	overtemperature protection release threshold temperature		90	100	110	°C	

[1] This parameter is not tested during production, by design it is guaranteed.

11.1 SSL2108X buck configuration

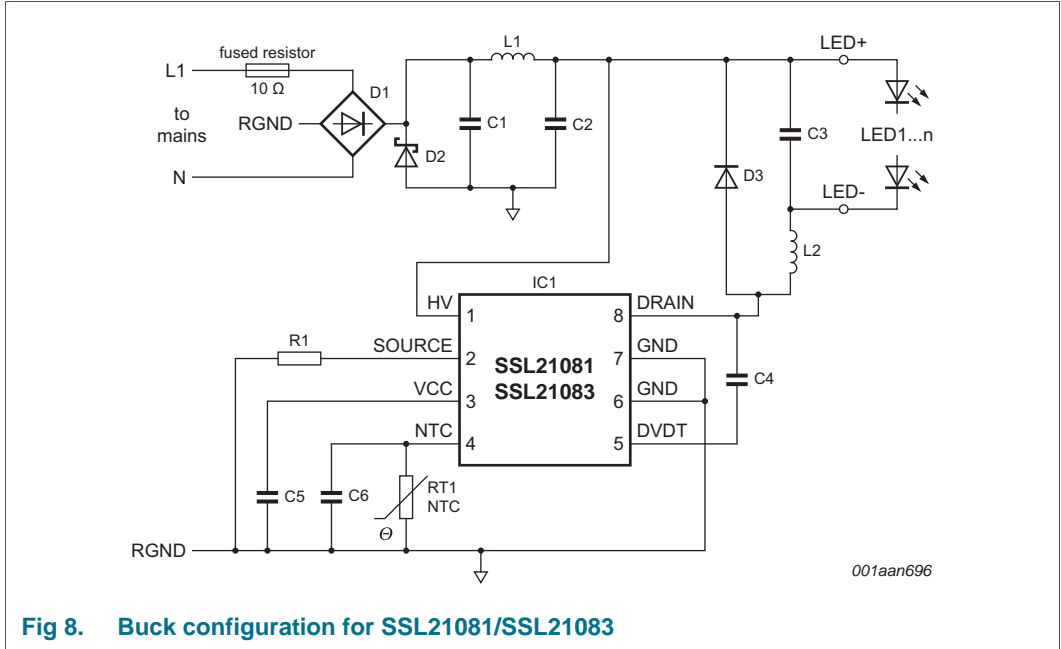


Fig 8. Buck configuration for SSL21081/SSL21083

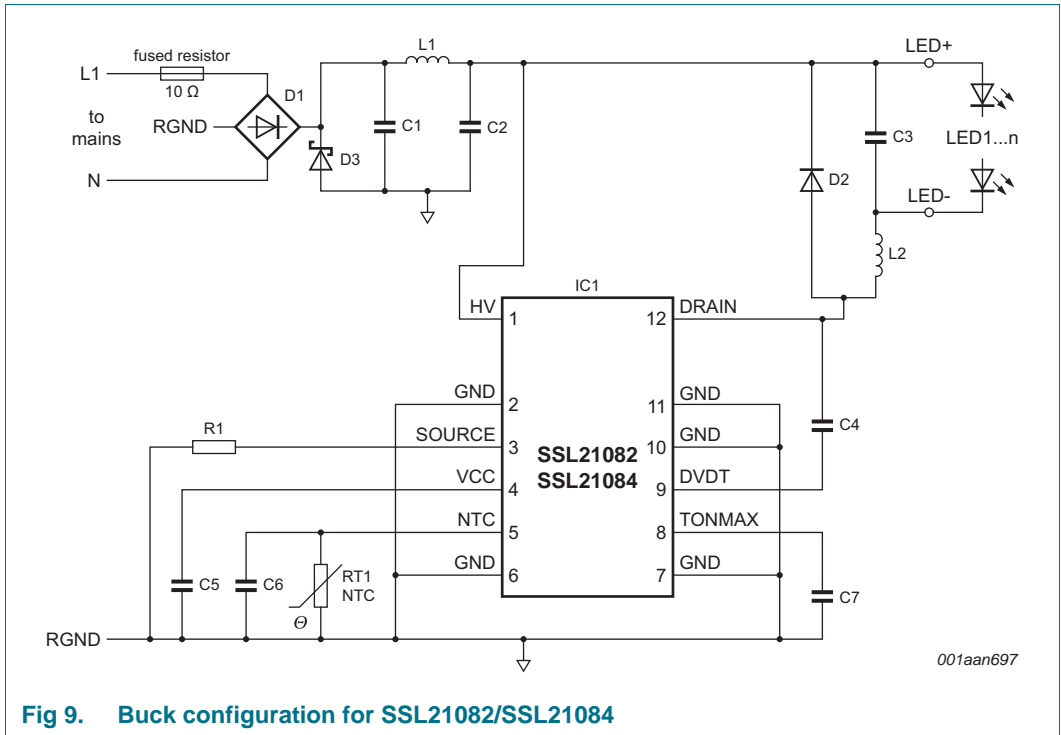


Fig 9. Buck configuration for SSL21082/SSL21084

Further application information can be found in the SSL2108X application note.



12. Package outline

S08: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1

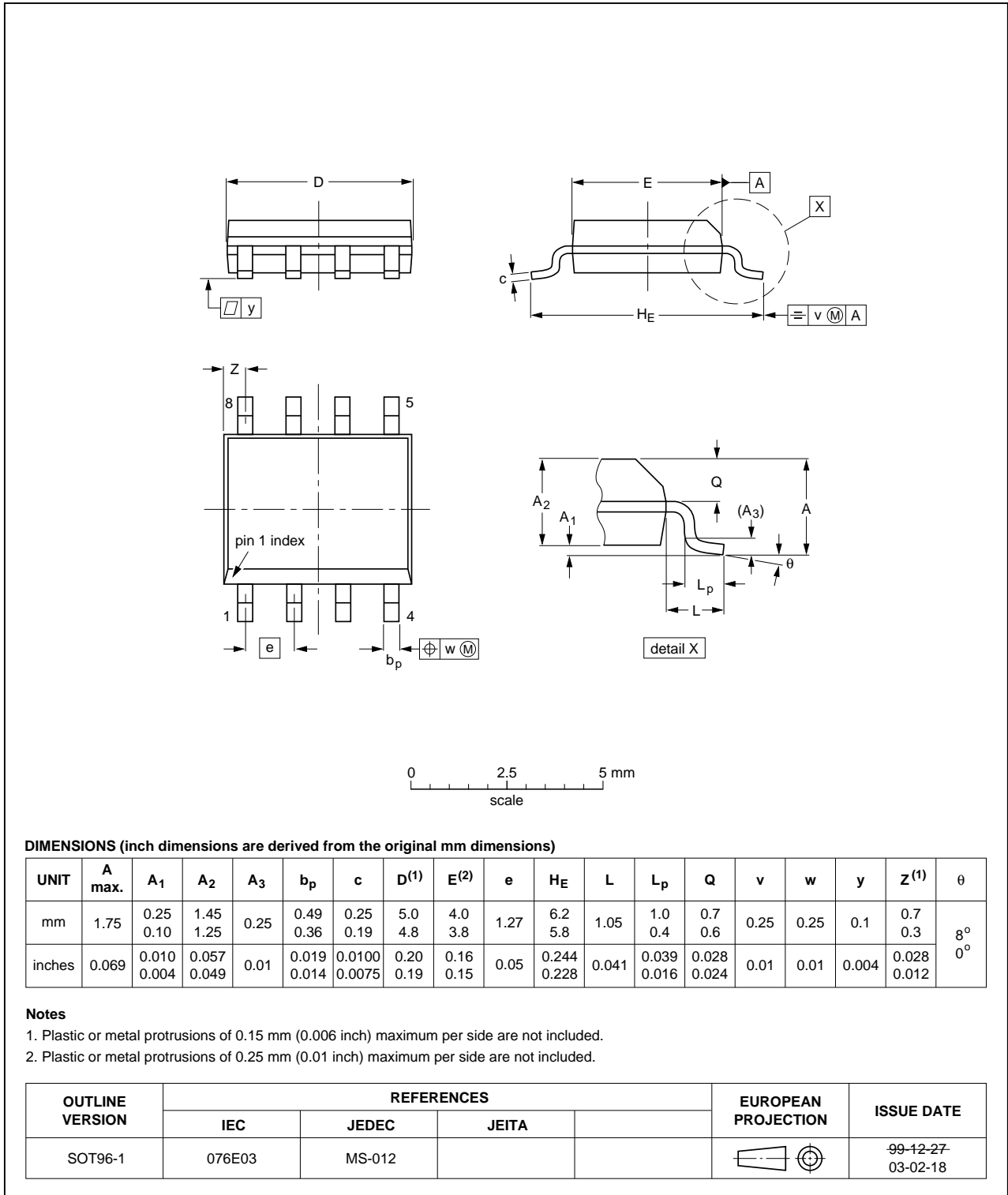


Fig 10. Package outline SOT96-1 (SOT8)

SO12: plastic small outline package; 12 leads; body width 3.9 mm

SOT1196-1

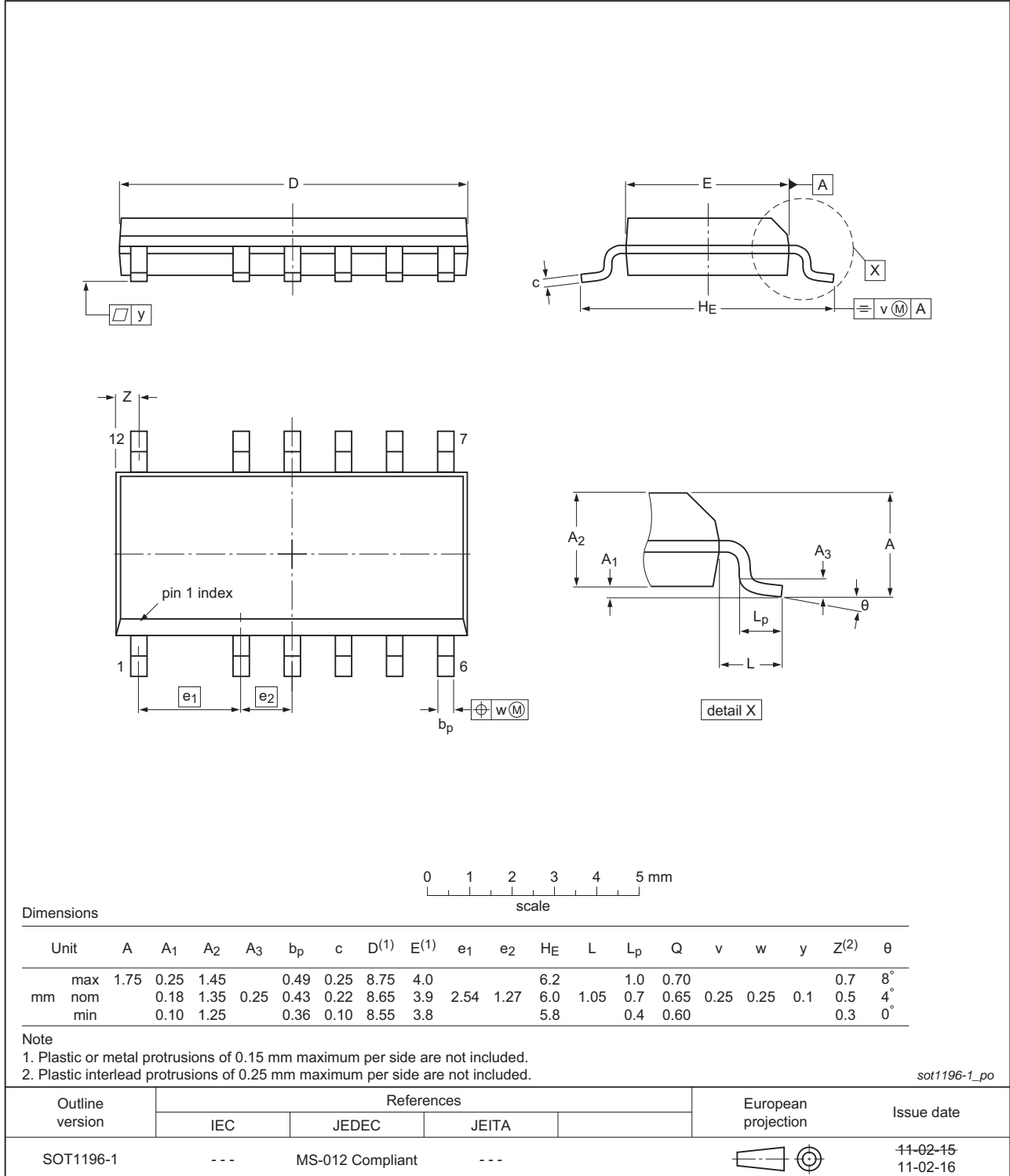


Fig 11. Package outline SOT1196-1 (SO12)

## 13. Abbreviations

Table 8. Abbreviations

Acronym	Description
BCM	Boundary Conduction Mode
BOM	Bill Of Materials
LED	Light Emitting Diode
LEB	Leading-Edge Blanking
MOSFET	Metal-Oxide Semiconductor Field-Effect Transistor
OCP	OverCurrent Protection
OSP	Output Short Protection
OTP	OverTemperature Protection
PCB	Printed-Circuit Board
PWM	Pulse-Width Modulation
SWP	Short-Winding Protection
UVLO	UnderVoltage LockOut
ZCS	Zero Current Switching

## 14. References

- [1] **SSL2108X** — Drivers for LED lighting - application note

## 15. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
SSL2108X v.1	20110909	Preliminary data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## 18. Tables

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Table 1.	Quick reference data	2
Table 2.	Ordering information	3
Table 3.	Ordering options	3
Table 4.	Pin description	5
Table 5.	Limiting values	12
Table 6.	Thermal characteristics	13
Table 7.	Characteristics	13
Table 8.	Abbreviations	19
Table 9.	Revision history	20

**continued >>**

**19. Figures**

Fig 1. Block diagram SSL2108X .....4  
 Fig 2. Pin configuration for SSL2108X (SO8) .....4  
 Fig 3. Pin configuration for SSL2108X (SO12) .....4  
 Fig 4. Basic application diagram SSL2108X (SO8 variant) .....6  
 Fig 5. Buck waveforms and valley detection .....7  
 Fig 6. NTC control curve .....10  
 Fig 7.  $R_{th(j-a)}$  versus board dimensions .....11  
 Fig 8. Buck configuration for SSL21081/SSL21083 ...16  
 Fig 9. Buck configuration for SSL21082/SSL21084 ...16  
 Fig 10. Package outline SOT96-1 (SOT8).....17  
 Fig 11. Package outline SOT1196-1 (SOT12).....18

**continued >>**



**20. Contents**

<b>1</b>	<b>General description</b> .....	<b>1</b>	<b>19</b>	<b>Figures</b> .....	<b>24</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>	<b>20</b>	<b>Contents</b> .....	<b>25</b>
<b>3</b>	<b>Applications</b> .....	<b>2</b>			
<b>4</b>	<b>Quick reference data</b> .....	<b>2</b>			
<b>5</b>	<b>Ordering information</b> .....	<b>3</b>			
5.1	Ordering options .....	3			
<b>6</b>	<b>Block diagram</b> .....	<b>4</b>			
<b>7</b>	<b>Pinning information</b> .....	<b>4</b>			
7.1	Pinning .....	4			
7.2	Pin description .....	5			
<b>8</b>	<b>Functional description</b> .....	<b>5</b>			
8.1	Introduction .....	5			
8.2	Converter operation .....	5			
8.3	Conversion frequency .....	6			
8.4	Valley detection .....	6			
8.5	Protections .....	7			
8.5.1	UnderVoltage LockOut (UVLO) .....	7			
8.5.2	Leading-Edge Blanking (LEB) .....	8			
8.5.3	OverCurrent Protection (OCP) .....	8			
8.5.4	OverTemperature Protection (OTP) .....	8			
8.5.5	Brownout protection .....	8			
8.5.6	Short-Winding Protection (SWP) .....	8			
8.5.7	Output Short Protection (OSP) .....	8			
8.6	VCC supply .....	9			
8.7	DVDT supply .....	9			
8.8	VCC regulator .....	9			
8.9	NTC functionality and PWM dimming .....	9			
8.9.1	Soft-start function .....	10			
8.10	Heat sink .....	10			
<b>9</b>	<b>Limiting values</b> .....	<b>12</b>			
<b>10</b>	<b>Thermal characteristics</b> .....	<b>13</b>			
<b>11</b>	<b>Characteristics</b> .....	<b>13</b>			
11.1	SSL2108X buck configuration .....	16			
<b>12</b>	<b>Package outline</b> .....	<b>17</b>			
<b>13</b>	<b>Abbreviations</b> .....	<b>19</b>			
<b>14</b>	<b>References</b> .....	<b>19</b>			
<b>15</b>	<b>Revision history</b> .....	<b>20</b>			
<b>16</b>	<b>Legal information</b> .....	<b>21</b>			
16.1	Data sheet status .....	21			
16.2	Definitions .....	21			
16.3	Disclaimers .....	21			
16.4	Trademarks .....	22			
<b>17</b>	<b>Contact information</b> .....	<b>22</b>			
<b>18</b>	<b>Tables</b> .....	<b>23</b>			

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